



TSMC Files Annual Report on Form 20-F for 2018

Hsinchu, Taiwan, R.O.C. – April 17, 2019 - TSMC (TWSE: 2330, NYSE: TSM), today filed its 2018 annual report on Form 20-F with the U.S. Securities and Exchange Commission.

The report is available at <http://www.tsmc.com/download/ir/secFillings/20F-2018.pdf>.

Hard copies of the report are also available, free of charge, upon request via

<https://app.irdirect.net/company/49733/hotline/>.

About TSMC

TSMC pioneered the pure-play foundry business model when it was founded in 1987 and has been the world's largest dedicated semiconductor foundry ever since. The Company supports a thriving ecosystem of global customers and partners with the industry's leading process technology and portfolio of design enablement solutions to unleash innovation for the global semiconductor industry.

TSMC serves its customers with annual capacity of about 12 million 12-inch equivalent wafers in 2019 from fabs in Taiwan, the United States, and China, and provides the broadest range of technologies from 0.5 micron plus all the way to foundry's most advanced processes, which is 7-nanometer today. TSMC is the first foundry to provide 7-nanometer production capabilities and is headquartered in Hsinchu, Taiwan. For more information about TSMC please visit <http://www.tsmc.com>.

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